

REMARKS

Applicants' undersigned representative wishes to thank the Examiner for the courtesies and thoughtful treatment afforded during the August 4, 2003 personal interview. The amendments made herein are based on the interview.

In the interview, the reasons for non-entry of the Amendment After Final dated May 13, 2003 were discussed. In particular the Examiner stated that the amendments to the claims might raise new issues that would require further consideration.

In addition and during the interview, a claim proposal was discussed, but the Examiner indicated that it would be beneficial to provide greater specificity in the definition of the connection state maintaining means.

The above amendment to Claim 1 follows through on this indication. Specifically, Claim 1 now indicates that each of a plurality of soldering through holes has an inner peripheral surface and a pair of lands each formed continuously across the opposite surfaces of a substrate therewith, and that a connection state maintaining means maintains a connection portion in a state not wetted by solder and maintains at least one land of the pair of lands, except for the connection portion, in a state wetted by solder.

At the interview, the Examiner raised questions over her interpretation of Figure 7. Modifications to that figure and to Figure 8 are now being contemplated. If the Examiner reaches this case before she has received word on whether drawing changes will be filed, she is requested to contact the undersigned at our Costa Mesa, California office, at (714) 540-8700.

All correspondence should continue to be directed to our below-listed
address.

Respectfully submitted,



Attorney for Applicants

Registration No. 50,325

FITZPATRICK, CELLA, HARPER & SCINTO
30 Rockefeller Plaza
New York, New York 10112-2200
Facsimile: (212) 218-2200

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